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Substitute for form 1449A/PTO		<b>Complete if Known</b>			
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)		<b>Application Number</b>	<b>09/922,974 - 1442</b>		
		<b>Filing Date</b>	<b>August 6, 2001</b>		
		<b>First Named Inventor</b>	<b>Theodore M. Bloomstein et al</b>		
		<b>Art Unit</b>	<b>1752 — 1752</b>		
		<b>Examiner Name</b>	<b>Not Yet Assigned SA-CAR</b>		
<b>Sheet</b>	<b>1</b>	<b>of</b>	<b>3</b>	<b>Attorney Docket Number</b>	<b>101328-159</b>

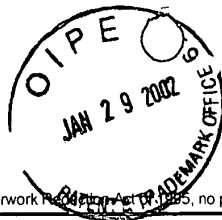
U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. <sup>1</sup>	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code <sup>2</sup> (if known)			
LS	A	4,575,330	03/11/1986	Hull	

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T <sup>6</sup>
		Country Code <sup>3</sup> -Number <sup>4</sup> -Kind Code <sup>5</sup> (if known)				

<sup>1</sup> Applicant's unique citation designation number (optional). <sup>2</sup> See attached Kinds Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov) or MPEP 901.04. <sup>3</sup> Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup> For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the application number of the patent document. <sup>5</sup> Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup> Applicant is to place a check mark here if English language Translation is attached.

OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS					
Examiner Initials	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, page(s), volume-issue number(s), publisher, city and/or country where published			T <sup>2</sup>
LS	B	J.M. MORAN AND D. MAYDAN, "High Resolution, Steep Profile Resist Patterns," <i>J. Vac. Sci. Technol.</i> <b>16</b> (6):1620-1624(1979).			TC 1700
LS	C	M. HATZAKIS, "PMMA Copolymers as High Sensitivity Electron Resists," <i>J. Vac. Sci. Technol.</i> , <b>16</b> (6):1984-1988(1979).			
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Substitute for form 1449B/PTO		Complete if Known			
INFORMATION DISCLOSURE STATEMENT BY APPLICANT  (use as many sheets as necessary)		Application Number	09/922,974 - 1442		
		Filing Date	August 6, 2001		
		First Named Inventor	Theodore M. Bloomstein et al		
		Group Art Unit	1752-1750		
		Examiner Name	Not Yet Assigned SAGWZ		
Sheet	2	of	3	Attorney Docket Number	101328-159

10	P	A.B. FRAZIER AND M.G. ALLEN, "Metallic Microstructures Fabricated Using Photosensitive Polyimide Electroplating Molds," <i>J. of Microelectromechanical Systems</i> 2(2):87-94(1993).	TC 170C	
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10	T	K. IKUTA, K. HIROWATARI, T. OGATA, "Three Dimensional Micro Integrated Fluid Systems (MIFS) Fabricated by Stereo Lithography," <i>Proceedings IEEE Micro Electro Mechanical Systems. An Investigation of Micro Structures, Sensors, Actuators, Machines and Robotic Systems (Cat. No. 94CH3404-1)</i> (IEEE, New York, NY, USA; 1994), pp. 1		
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10	AD	B.H. CUMPSTON, J.E. EHRLICH, S.M. KUEBLER, M. LIPSON, S.R. MARDER, D. MCCORD-MAUGHTON, J. W. PERRY, H. ROCKEL, AND M. RUMI, "Three-dimensional Microfabrication Using Two-photon Polymerization," <i>SPIE</i> 3512:168(1998).		
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10	AG	KILIE A. ROBERT, MICHAEL B. THOMPSON "Finer Features for Functional Microdevices," <i>Nature Vol. 412:697-698(2001)</i>		
Examiner Signature		10/2/03	Date Considered	7/2/03

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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